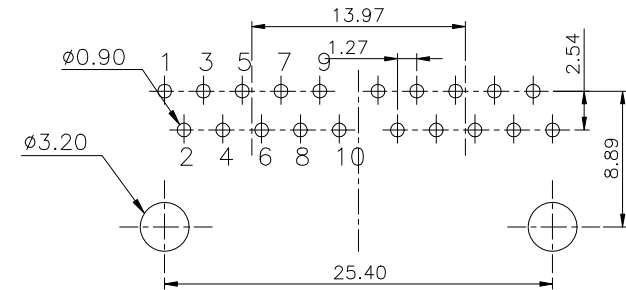
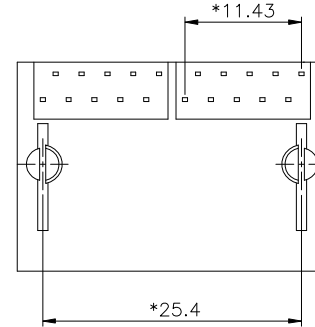
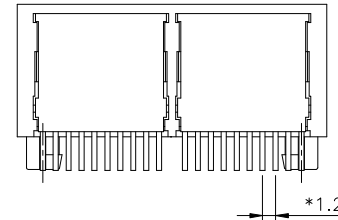
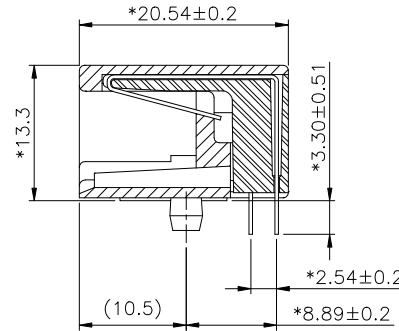
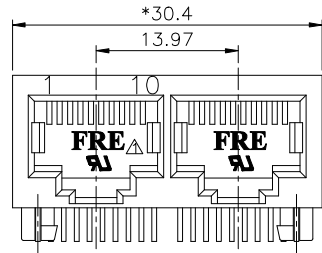


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		DRAWING MODIFY	LGY 11/26/02	
△		ADD PART NO.	QIANPU 3/31/04	
△		ADD PART NO.	QIANPU 11/14/04	
△		ADD PART NO.	LIUXIN 02/23/05	



PC Board Layout
Component Side Shown

NOTES:

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS MIN.
- CURRENT RATING : 1.5 AMP MIN.
- CONTACT RESISTANCE : 45 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

- HOUSING MATERIAL : PBT+30% G.F. UL94V-0 OR PA9T OR FR52. △
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

- STORAGE : -40°C TO +85°C.
- OPERATION: 0°C TO 70°C.

MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.

CUL FILE NO. E163191

PART NUMBER: E590X-00A0XX

NO. OF CONTACT
8- 8 CONTACTS
1-10 CONTACTS

1- 3u" 2- 6u" 3-15u"
4-30u" 5-50u"

△ 4- W/ "FRE" LOGO
J- W/O "FRE" LOGO

△ LEAD FREE P/N: E590X-00AXXX-L

NO. OF CONTACT
8- 8 CONTACTS
1-10 CONTACTS

1- 3u" 2- 6u" 3-15u"
4-30u" 5-50u"

W4- W/ "FRE" LOGO, HOUSING MATERIAL: PA9T
WJ- W/O "FRE" LOGO, HOUSING MATERIAL: PA9T
34- W/ "FRE" LOGO, FR52 BK △

← MM (INCH) →		DFTO BASS	DATE 2/17/98	FULL RISE ELECTRONIC CO., LTD	
TOLERANCES EXCEPT AS NOTED		CHKD QIANPU	DATE 2005/2/25		
MM	±	MFO	DATE	TITLE 20.57 FLANGELESS PCB JACK 10P	
.0 ±0.20	±	APV LUSHEN	DATE 2005/2/25		
.00 ±0.15	±	MATERIAL :		DRAWING NO. GE593037	
.000 ±0.075	±	FINISH :		SIZE A3	REV 4
ANGLES ±		QTY :		/PART NO. SEE NOTE	
THIRD ANGLE PROJECTION		SCALE : 2:1		DO NOT SCALE DRAWING	
				SHEET X	OF Y